

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YI FAN HU	07/09/2021
YE FENG ZHENG	07/07/2021
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<b>Postal Code:</b>	518057
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17383724
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<b>ATTORNEY DOCKET NUMBER:</b>	Q264944
<b>NAME OF SUBMITTER:</b>	QIANA GRAHAM, NEW APP DEPT
<b>SIGNATURE:</b>	/Qiana Graham/
<b>DATE SIGNED:</b>	07/23/2021
<b>Total Attachments: 4</b>	
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# ASSIGNMENT WITH DECLARATION FOR PATENT APPLICATION (37 CFR 1.63)

## 專利申請轉讓聲明書(37 CFR 1.63)

### Chinese Language Assignment with Declaration

鑒於，我 / 我們，即下面簽名之發明人（以下簡稱「轉讓人」），已發明下文確認之申請中所述的若干改善之處；和

鑒於，\_\_\_\_\_（地址位於\_\_\_\_\_）（「承讓人」）意欲購買申請和發明以及就此隨後獲取的任何美國專利中的全部權利、所有權和權益；

因此，就有值代價而言，相關收據特此確認：

我 / 我們，上文指名轉讓人，特此向上文指名承讓人及其繼承人和受讓人出售、轉讓及出讓該申請中適用於美利堅合眾國的全部權利、所有權和權益，及該申請中披露的適用於美利堅合眾國的發明（包括該申請的所有分案和延續申請），及可能據此頒發的所有美國專利證書及所有再頒發之專利證書（包括35 USC 119項下的要求優先權的權利及就過往損害賠償提起訴訟的權利），及適用於所有其他國家的發明（包括經修訂1883年巴黎國際公約項下的優先權）；我 / 我們請求美國專利及商標局局長向承讓人及其繼承人和受讓人簽發該申請中所載列之發明的任何專利證書；及我 / 我們特此同意承讓人可申請外國發明之專利證書，且我 / 我們將會應承讓人的要求，無償簽立承讓人申請美國和外國專利所必需的所有文件。

（合法化審批無需記錄，但須作為35 USC 261項下執行的表面證據）

作為下述發明人，我特此聲明：

該轉讓聲明書乃有關：

- ☐ 隨附的申請或
- ☐ 於\_\_\_\_\_日提交的  
美國專利申請或PCT國際申請號碼  
\_\_\_\_\_。

該申請有權：

\_\_\_\_\_

\_\_\_\_\_

\_\_\_\_\_

Whereas, I/We, the undersigned inventor(s) hereinafter called assignor(s), have invented certain improvements described in the application identified below; and

Whereas, TENCENT TECHNOLOGY (SHENZHEN) COMPANY LIMITED of 35/F, Tencent Building, Kejizhongyi Road, Midwest District of Hi-tech Park, Nanshan District, Shenzhen, Guangdong, 518057, China, (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, and all countries foreign thereto, including rights of priority under the International Convention of Paris (1883) as amended, including the right to claim priority under 35 USC 119 and the right to sue for past damages, and I/we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we hereby agree that the assignee may apply for foreign Letters Patent on the invention and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States and foreign applications when called upon to do so by the assignee.

(Legalization not required for recording but is prima facie evidence of execution under 35 USC 261)

As the below named inventor, I hereby declare that:

This assignment with declaration is directed to:

- ☒ The attached application, or
- ☐ United States Application or PCT International Application  
Number \_\_\_\_\_ filed on \_\_\_\_\_.

The application is entitled:

3D IMAGE CLASSIFICATION METHOD AND APPARATUS,  
DEVICE, AND STORAGE MEDIUM

### Chinese Assignment with Declaration

我已做出或授權他人做出上述確認的申請。

我相信我是申請中要求保護的發明的原始發明人或原始聯合發明人之一。

我已讀閱並了解提出該轉讓聲明的申請內容。

根據37 CFR 1.56之規定，我知悉我有義務向專利局透露據我所知的有關專利性的所有實質性資訊。

特此確認，根據18 USC 1001之規定，於本轉讓聲明書中蓄意做出任何虛假聲明會被處以罰款或五（5）年以下監禁或兩者並罰。

The above identified application was made or was authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application for which this assignment with declaration is being submitted.

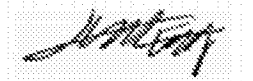
I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR 1.56.

I hereby acknowledge that any willful false statement made in this assignment with declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

#### STATEMENT OF ACCURATE TRANSLATION IN ACCORDANCE WITH 37 CFR 1.69(b):

The assignment with declaration is an accurate translation of the corresponding English language assignment with declaration.

Signature



Date

March 17, 2014

## NAME OF SOLE OR FIRST INVENTOR:

唯一發明人或第一發明人姓名:

Yifan Hu

Given Name (first and middle [if any])

名字 (名和中名 [若有])

Yi Fan

Family Name or Surname

姓氏

HU

Inventor's signature

發明人簽名

[Signature]

Date

日期

2021/07/09

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## NAME OF SECOND INVENTOR:

第二發明人姓名:

Given Name (first and middle [if any])

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姓氏

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## NAME OF SECOND INVENTOR:

第二發明人姓名:

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Family Name or Surname

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Inventor's signature

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Mailing Address:

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PATENT

RECORDED: 07/23/2021

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